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A circular black ink stamp. The outer ring contains the text "OIPE" at the top and "JCA" at the bottom. The center of the stamp contains the date "APR 22 2002". Below the date, the words "PATENT & TRADEMARK" are visible, partially cut off by the bottom edge of the stamp.

PTO/SB/08A (10-96)

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Substitute for form 1449A/PTO

Complete if Known

(use as many sheets as necessary)

Application Number	10/029,456
Filing Date	December 21, 2001
First Named Inventor	Douglas G. Ivey et. al
Group Art Unit	1775
Examiner Name	
Attorney Docket Number	RR-496

U.S. PATENT DOCUMENTS

[illegible]

FOREIGN PATENT DOCUMENTS

Examiner Initials*	Cite No. ¹	Foreign Patent Document			Name of Patentee or Applicant of Cited Document	Date of Publication of Cited Document MM-DD-YYYY	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear	T ⁸
		Office ³	Number ⁴	Kind Code ⁶ (if known)				
<i>[Handwritten initials]</i>		CA	2,268,867 -		Ivey et. al.	10-13-2000		
		DE	4,406,434 ~		Hempel et. al.	08-10-1995		
		JP	56 136994 -		Konase et. al.	10-26-1981		
		JP	61 15992 _		Hamaguchi et. al.	04-26-1994		
		WO	98/03700 -		Kuhn et. al.	01-29-1998		

Examiner
Signature

John Zimmerman

Date
Cons

4/30/03

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

¹ Unique citation designation number. ² See attached Kinds of U.S. Patent Documents. ³ Enter Office that issued the document, by the two-letter code (WIPO Standard ST.3). ⁴ For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document. ⁵ Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST. 16 if possible. ⁶ Applicant is to place a check mark here if English language Translation is attached.

Burden Hour Statement: This form is estimated to take 2.0 hours to complete. Time will vary depending upon the needs of the individual case. Any comments on the amount of time you are required to complete this form should be sent to the Chief Information Officer, Patent and Trademark Office, Washington, DC 20231. **DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Assistant Commissioner for Patents, Washington, DC 20231.**

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APR 22 2002

PTO/SB/06B (10-96)
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Substitute for form 1449B/PTO			Complete if Known		
INFORMATION DISCLOSURE STATEMENT BY APPLICANT (use as many sheets as necessary)			Application Number	10/029,456	
			Filing Date	December 21, 2001	
			First Named Inventor	Douglas G. Ivey et al.	
			Group Art Unit	1775	
			Examiner Name		
Sheet	2	of	2	Attorney Docket Number	RR-496

OTHER PRIOR ART – NON PATENT LITERATURE DOCUMENTS				
Examiner Initials*	Cite No. ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²	
JZ	-	Kallmayer, C. et. al., "Fluxless Flip-Chip Attachment Techniques Using the Au/Sn Metallurgy," IEEE/CPMT International Electronics Manufacturing Technology Symposium, 1995, pp. 20-28. (no marks)		
JZ	-	Kallmayer, C. et. al., "Fluxless Flip-Chip Soldering Using the Eutectic Gold-Tin System - A Comparison between Self-Alignment and Thermode-Bonding," 10th European Microelectronics Conference, 1995, pp. 440-449.		
JZ	-	Zakel, E. and Reichl, Herbert, "Flip Chip Assembly Using Gold, Gold-Tin, and Nickel-Gold Metallurgy," Flip-Chip Technologies, ed., J. Lau, McGraw-Hill, (1995), pp. 415-468. (no marks)		
JZ	-	Mason, D.R. et. al., "Alloy Gold Deposits: Have They Any Industrial Use?" Transactions of the Institute of Metal Finishing, 1974, Volume 52, pp. 143-148. (no marks)		
JZ	-	Raub, E. and Bihlmaier, K., "Galvanische Weissgoldniederschläge," Mitteilungen Des Forschungsinstituts und Proberamts für Edelmetalle an der Staatl. 11 Jahrgang, Nr. 7/8, Okt./Nov. 1937, pp. 59-71.		
JZ	-	Kubota, N. et. al., "Electrodeposition of Gold-Tin Alloys from the Pyrophosphate Solution," J. Met. Fin. Soc. Japan, 34 (1983) No. 1, pp. 37-43. (no marks)		
JZ	-	Tanabe, Y. et. al., "On the Microstructure and the Phase of Electrodeposited Au-Sn and Ag-Sn Alloys," J. Met. Fin. Soc. Japan, 34 (1983) No.9, pp. 8-15. (no marks)		
JZ	-	Kubota, N., et. al., "Conductivity and Ion Transport In Gold-Tin Pyrophosphate Baths," Plating and Surface Finishing, 71 (1984) March, pp. 46-49.		

Examiner Signature	John Zimmerman	Date Considered	4/30/03
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